DATA SHEET

NEC

GaAs INTEGRATED CIRCUIT

μPG2045TQ

L-BAND SP3T SWITCH

DESCRIPTION

The μPG2045TQ is an L-band SP3T GaAs FET switch which was developed for CDMA/PCS/GPS triple mode digital cellular telephone application. The device can operate from 500 MHz to 2.0 GHz, having the low insertion loss and high linality by 2.4 V low control voltage.

FEATURES

- Low insertion loss : L_{INS} = 0.28 dB TYP. @ ANT-RF2, V_{cont} = +2.4 V/0 V, f = 1.0 GHz
  : L_{INS} = 0.38 dB TYP. @ ANT-RF2, V_{cont} = +2.4 V/0 V, f = 2.0 GHz
- High power : $P_{in\ (0.1\ dB)}$ = 32.0 dBm TYP. @ V_{cont} = +2.4 V/0 V, f = 1.0 GHz
- High-density surface mounting : 10-pin plastic TSON package (2.30 × 2.55 × 0.60 mm)

APPLICATION

- CDMA/PCS/GPS triple mode digital cellular telephone etc.

ORDERING INFORMATION

Part Number	Package	Marking	Supplying Form
μPG2045TQ-E1	10-pin plastic TSON	2045	• Embossed tape 8 mm wide • Pin 5, 6 face the perforation side of the tape • Qty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office.
Part number for sample order: μPG2045TQ

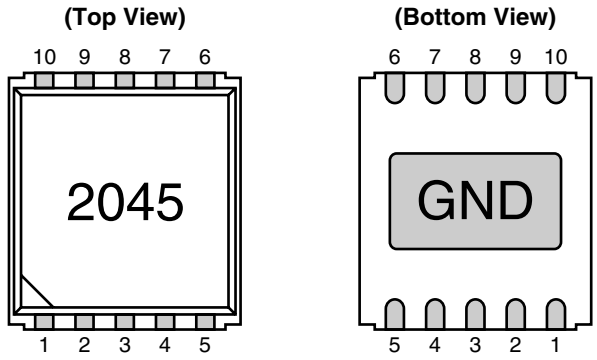
Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

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PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	RF1
2	GND
3	RF2
4	V_{cont2}
5	RF3
6	V_{cont3}
7	GND
8	ANT
9	GND
10	V_{cont1}

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Switch Control Voltage	V_{cont}	–6.0 to +6.0	V
Input Power	P_{in}	+36	dBm
Operating Ambient Temperature	T_A	–45 to +85	°C
Storage Temperature	T_{stg}	–55 to +150	°C

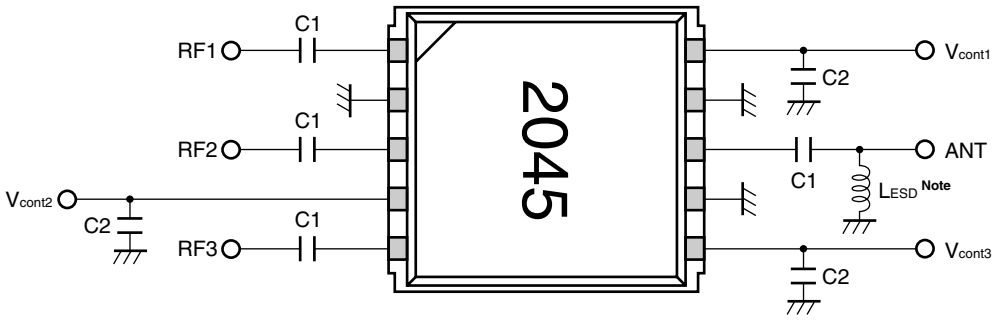
RECOMMENDED OPERATING RANGE (T_A = +25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Switch Control Voltage (High)	$V_{cont\ (H)}$	+2.4	+2.6	+5.0	V
Switch Control Voltage (Low)	$V_{cont\ (L)}$	–0.2	0	+0.2	V

ELECTRICAL CHARACTERISTICS (T_A = +25°C, V_{cont} = 2.4 V/0 V, Z_O = 50 Ω, off chip DC blocking capacitors value: 56 pF, unless otherwise specified)

Parameter	Symbol	Pass	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss	L_{INS}	ANT-RF2	f = 0.5 to 1.0 GHz	–	0.28	0.45	dB
			f = 1.0 to 2.0 GHz	–	0.38	0.55	dB
		ANT-RF1	f = 0.5 to 1.0 GHz	–	0.50	0.65	dB
		ANT-RF3	f = 1.0 to 2.0 GHz	–	0.65	0.80	dB
Isolation	ISL	ANT-RF1	f = 0.5 to 1.0 GHz	24	27	–	dB
		ANT-RF3	f = 1.0 to 2.0 GHz	18	21	–	dB
		ANT-RF2	f = 0.5 to 1.0 GHz	18	21	–	dB
			f = 1.0 to 2.0 GHz	13	15	–	dB
Input Return Loss	RL_{in}	ANT-RF1/2/3	f = 0.5 to 2.0 GHz	15	20	–	dB
Output Return Loss	RL_{out}	ANT-RF1/2/3	f = 0.5 to 2.0 GHz	15	20	–	dB
0.1 dB Gain Compression Input Power	$P_{in\ (0.1\ dB)}$	ANT-RF1/2/3	f = 1.0 GHz	30.0	32.0	–	dBm
2nd Harmonics	2f0	ANT-RF1/2/3	f = 1.0 GHz, P_{in} = +27 dBm	–	75	–	dBc
3rd Harmonics	3f0	ANT-RF1/2/3	f = 1.0 GHz, P_{in} = +27 dBm	–	75	–	dBc
Input 3rd Order Intercept Point	IIP_3	ANT-RF2	f = 882 MHz/883 MHz @ 1 MHz spacing, P_{in} = +24 dBm each @ 2 Tone	–	66	–	dBm
		ANT-RF1 ANT-RF3		–	64	–	dBm
		ANT-RF2	f = 1 960 MHz/1 961 MHz @ 1 MHz spacing, P_{in} = +16 dBm each @ 2 Tone	–	60	–	dBm
		ANT-RF1 ANT-RF3		–	58	–	dBm
Switch Control Speed	t_{sw}			–	150	–	ns
Switch Control Current	I_{cont}		RF Non	–	1	20	μA

EVALUATION CIRCUIT



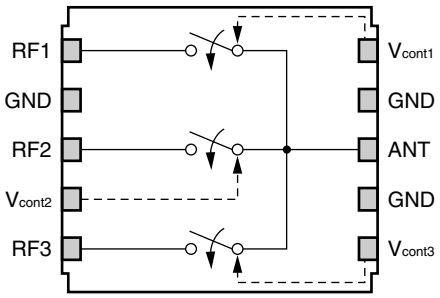
Note Recommend attached L_{ESD} to antenna port for ESD protection.

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

USING THE NEC EVALUATION BOARD

Symbol	Values
C1	56 pF
C2	1 000 pF

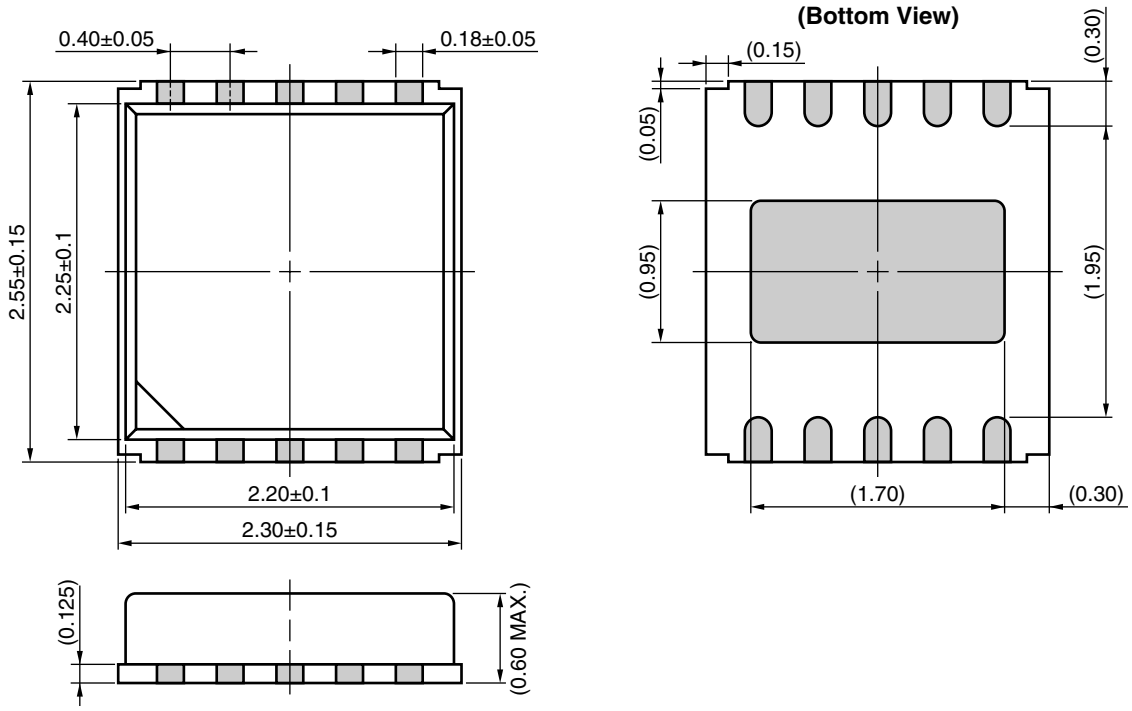
TRUTH TABLE



V_{cont1}	V_{cont2}	V_{cont3}	ANT-RF1	ANT-RF2	ANT-RF3
High	Low	Low	ON	OFF	OFF
Low	High	Low	OFF	ON	OFF
Low	Low	High	OFF	OFF	ON

PACKAGE DIMENSIONS

10-PIN PLASTIC TSON (UNIT: mm)



Remark ( ) : Reference value

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
VPS	Peak temperature (package surface temperature) Time at temperature of 200°C or higher Preheating time at 120 to 150°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 215°C or below : 25 to 40 seconds : 30 to 60 seconds : 3 times : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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M8E 00.4-0110

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▶**For further information, please contact**

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